## 502026598 08/16/2012

#### PATENT ASSIGNMENT

# Electronic Version v1.1 Stylesheet Version v1.1

SUBMISSION TYPE:	NEW ASSIGNMENT
NATURE OF CONVEYANCE:	ASSIGNMENT

#### **CONVEYING PARTY DATA**

Name	Execution Date
Wei-Chou Lan	03/15/2012
Ted-Hong Shinn	08/01/2012
Henry Wang	03/15/2012
Chia-Chun Yeh	08/01/2012

#### **RECEIVING PARTY DATA**

Name:	E Ink Holdings Inc.	
Street Address:	No. 3, Li-Hsin Rd.1, Science-Based Industrial Park,	
City:	Hsinchu	
State/Country:	TAIWAN	

#### PROPERTY NUMBERS Total: 1

Property Type	Number
Application Number:	13572711

### **CORRESPONDENCE DATA**

Fax Number: 5105807280

Email: usa@jcipgroup.com.tw

Correspondence will be sent to the e-mail address first; if that is unsuccessful, it will be sent

via US Mail.

Correspondent Name: JIANQ CHYUN INTELLECTUAL PROPERTY
Address Line 1: 7F.-1, NO. 100, ROOSEVELT RD., SEC. 2,

Address Line 4: Taipei, TAIWAN 100

ATTORNEY DOCKET NUMBER: 40197-US-PA

NAME OF SUBMITTER: Belinda Lee

Total Attachments: 2

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PATENT

REEL: 028794 FRAME: 0542

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## **ASSIGNMENT**

#### WHEREAS,

1. Wei-Chou Lan

2. Ted-Hong Shinn

3. Henry Wang

4. Chia-Chun Yeh

hereinafter referred to as ASSIGNOR, has/have invented certain new and useful improvements as described and set forth in the below identified application for United States Letters Patent:

Title: THREE-DIMENSION CIRCUIT STRUCTURE AND SEMICONDUCTOR DEVICE

[] Filed:

Serial No.

[x] Executed concurrently with the execution of this instrument

WHEREAS, E Ink Holdings Inc.

of No. 3, Li-Hsin Rd.1, Science-Based Industrial Park, Hsinchu, Taiwan, R.O.C.

hereinafter referred to as ASSIGNEE, is desirous of acquiring ASSIGNOR'S interest in the said invention and application and in any U.S. Letters Patent which may be granted on the same:

NOW, THEREFORE, TO ALL WHOM IT MAY CONCERN: Be it known that, for good and valuable consideration, receipt of which is hereby acknowledged by Assignor, Assignor has/have sold, assigned and transferred, and by these presents does/do sell, assign and transfer unto the said Assignee, and Assignee's successors and assigns, all his/her/their rights, title and interest in and to the said invention and application and all future improvements thereon, and in and to any Letters Patent which may hereafter be granted on the same in the United States, the said interest to be held and enjoyed by said Assignee as fully and exclusively as it would have been held and enjoyed by said Assignor had this Assignment and transfer not been made, to the full end and term of any Letters Patent which may be granted thereon, or of any division, renewal, continuation in whole or in part, substitution, conversion, reissue, prolongation or extension thereof.

Assignor further agrees/agree that he/she/they will, without charge to said Assignee, but at Assignee's expense, cooperate with Assignee in the prosecution of said application and/or applications, execute, verify, acknowledge and deliver all such further papers, including applications for Letters Patent and for the reissue thereof, and instruments of assignment and transfer thereof, and will perform such other acts as Assignee Lawfully may request, to obtain or maintain Letters Patent for said invention and improvement, and to vest title thereto in said Assignee, or Assignee's successors and assigns.

# ASSIGNMENT CONTINUED

IN TESTIMONY WHEREOF, Assignor has/have signed his/her/their name(s) on the date(s) indicated.

Signature: <u>(1) Qi - Qi on Lan</u> Sole or First Joint Inventor: Wei-Chou Lan	Date:	2012.03.15
The state of the s		
Signature: Tod-Hong Shin	Date:	Aug. 1, 2012
Second Joint Inventor (if any): Ted-Hong Shinn		
. /		
Signature: Manp	Date:	7212.3.15
Third Joint Inventor (if any). Henry Wang		
Signature: Chia-Chun Yeh	Date:	Aug. 1, 2012

Fourth Joint Inventor (if any): Chia-Chun Yeh